INTEGRATED CIRCUITS

DATA SHEET

TDA4686Video processor with automatic cut-off control

Product specification Supersedes data of May 1993 File under Integrated Circuits, IC02 1997 Jun 23





Video processor with automatic cut-off control

TDA4686

FEATURES

- Intended for double line frequency application (100/120 Hz)
- · Operates from an 8 V DC supply
- Black level clamping of the colour difference, luminance and RGB input signals with coupling-capacitor DC level storage
- Two analog RGB inputs, selected either by fast switch signals or via I²C-bus; brightness and contrast control of both RGB inputs
- Saturation, contrast, brightness and white adjustment via I²C-bus
- Same RGB output black levels for Y/CD and RGB input signals
- Timing pulse generation from either a 2 or 3-level sandcastle pulse for clamping, vertical synchronization and cut-off timing pulses
- Automatic cut-off control or clamped output selectable via I²C-bus
- Automatic cut-off control with picture tube leakage current compensation
- Cut-off measurement pulses after end of the vertical blanking pulse or end of an extra vertical flyback pulse
- · Increased RGB signal bandwidths
- Two switch-on delays to prevent discolouration before steady-state operation
- · Average beam current and peak drive limiting
- PAL/SECAM or NTSC matrix selection via I²C-bus
- Emitter-follower RGB output stages to drive the video output stages
- I²C-bus controlled DC output e.g. for hue-adjust of NTSC (multistandard) decoders
- · No delay of clamping pulse
- Large luminance, colour difference and RGB bandwidth.

GENERAL DESCRIPTION

The TDA4686 is a monolithic integrated circuit with a luminance and a colour difference interface for video processing in TV receivers. Its primary function is to process the luminance and colour difference signals from a colour decoder which is equipped e.g. with the multistandard decoder TDA4655 or TDA9160 plus delay line TDA4661 and the Picture Signal Improvement (PSI) IC, TDA467X, or from a feature module.



The required input signals are:

- · Luminance and negative colour difference signals
- 2 or 3-level sandcastle pulse for internal timing pulse generation
- I²C-bus data and clock signals for microcontroller control

Two sets of analog RGB colour signals can also be inserted, e.g. one from a peritelevision connector and the other from an on-screen display generator. The TDA4686 includes full I²C-bus control of all parameters and functions with automatic cut-off control of the picture tube cathode currents. It provides RGB output signals for the video output stages.

The TDA4686 is a simplified, pin compatible (except for pin 18) version of the TDA4680. The module address via I²C-bus can be used for both ICs; where a function is not included in the TDA4686 the I²C-bus command is not executed. The differences with the TDA4680 are:

- No automatic white level control; the white levels are determined directly by the I²C-bus data
- RGB reference levels for automatic cut-off control are not adjustable via I²C-bus
- · No clamping delay
- Only contrast and brightness adjust for the RGB input signals
- The measurement lines are triggered either by the trailing edge of the vertical component of the sandcastle pulse or by the trailing edge of an optional external vertical flyback pulse (on pin 18), according to which occurs first.

The TDA4685 is like TDA4686 but intended for normal line frequency application.

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QUICK REFERENCE DATA

| SYMBOL | PARAMETER | MIN. | TYP. | MAX. | UNIT |
|---------------------|---|------|------|------|------|
| V _P | supply voltage (pin 5) | 7.2 | 8.0 | 8.8 | V |
| lР | supply current (pin 5) | _ | 60 | _ | mA |
| V _{8(p-p)} | luminance input (peak-to-peak value) | _ | 0.45 | _ | V |
| V _{6(p-p)} | -(B - Y) input (peak-to-peak value) | _ | 1.33 | _ | V |
| V _{7(p-p)} | -(R - Y) input (peak-to-peak value) | _ | 1.05 | _ | V |
| V ₁₄ | 3-level sandcastle pulse | | | | |
| | H + V | _ | 2.5 | _ | V |
| | н | _ | 4.5 | _ | V |
| | BK | _ | 8.0 | _ | V |
| | 2-level sandcastle pulse | | | | |
| | H + V | _ | 2.5 | _ | V |
| | BK | _ | 4.5 | _ | V |
| V _{i(p-p)} | RGB input signals at pins 2, 3, 4, 10, 11 and 12 (peak-to-peak value) | _ | 0.7 | _ | V |
| V _{o(b-w)} | RGB outputs at pins 24, 22 and 20 (black-to-white value) | _ | 2.0 | _ | V |
| T _{amb} | operating ambient temperature | 0 | _ | 70 | °C |

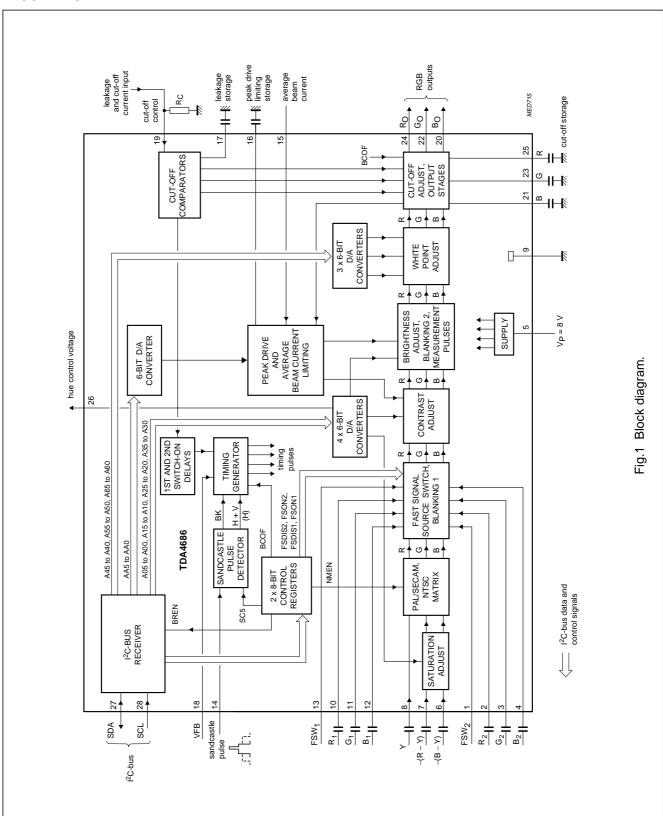
ORDERING INFORMATION

| TYPE NUMBER | | PACKAGE | |
|---------------|----------------------|--|----------|
| I TPE NOWIBER | NAME DESCRIPTION VEF | | VERSION |
| TDA4686 | DIP28 | plastic dual in-line package; 28 leads (600 mil) | SOT117-1 |
| TDA4686WP | PLCC28 | | |

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BLOCK DIAGRAM



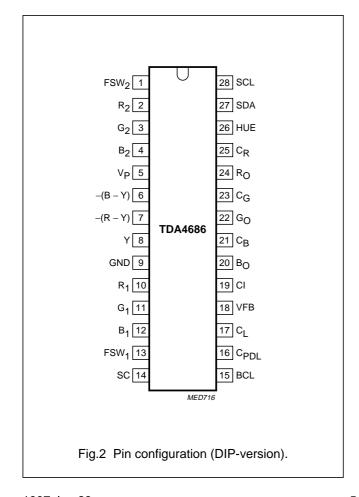
Video processor with automatic cut-off control

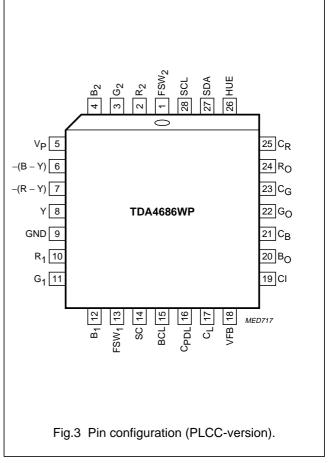
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PINNING

| SYMBOL | PIN | DESCRIPTION |
|------------------|-----|-------------------------------------|
| FSW ₂ | 1 | fast switch 2 input |
| R ₂ | 2 | red input 2 |
| G ₂ | 3 | green input 2 |
| B ₂ | 4 | blue input 2 |
| V _P | 5 | supply voltage |
| -(B - Y) | 6 | colour difference input –(B – Y) |
| -(R - Y) | 7 | colour difference input –(R – Y) |
| Υ | 8 | luminance input |
| GND | 9 | ground |
| R ₁ | 10 | red input 1 |
| G ₁ | 11 | green input 1 |
| B ₁ | 12 | blue input 1 |
| FSW ₁ | 13 | fast switch 1 input |
| SC | 14 | sandcastle pulse input |
| BCL | 15 | average beam current limiting input |

| SYMBOL | PIN | DESCRIPTION |
|------------------|-----|---|
| C _{PDL} | 16 | storage capacitor for peak drive limiting |
| C _L | 17 | storage capacitor for leakage current |
| VFB | 18 | vertical flyback pulse input |
| CI | 19 | cut-off measurement input |
| B _O | 20 | blue output |
| C _B | 21 | blue cut-off storage capacitor |
| G _O | 22 | green output |
| C_{G} | 23 | green cut-off storage capacitor |
| R _O | 24 | red output |
| C _R | 25 | red cut-off storage capacitor |
| HUE | 26 | hue control output |
| SDA | 27 | I ² C-bus serial data input; acknowledge output |
| SCL | 28 | I ² C-bus serial clock input |





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I²C-BUS PROTOCOL

Control

The I²C-bus transmitter provides the data bytes to select and adjust the following functions and parameters:

- · Brightness adjust
- · Saturation adjust
- Contrast adjust
- · DC output e.g. for hue control
- · RGB gain adjust
- · Peak drive limiting level adjust
- Selects either 3-level or 2-level (5 V) sandcastle pulse
- Enables cut-off control; enables output clamping
- · Selects either PAL/SECAM or NTSC matrix
- Enables/disables synchronization of the execution of I²C-bus commands with the vertical blanking interval
- Enables Y/CD, RGB₁ or RGB₂ input.

I²C-bus transmitter and data transfer

I²C-BUS SPECIFICATION

The I²C-bus is a bidirectional, two-wire, serial data bus for intercommunication between ICs in an equipment. The microcontroller transmits data to the I²C-bus receiver in the TDA4686 over the serial data line SDA (pin 27) synchronized by the serial clock line SCL (pin 28). Both lines are normally connected to a positive voltage supply through pull-up resistors. Data is transferred when the SCL line is LOW. When SCL is HIGH the serial data line SDA must be stable. A HIGH-to-LOW transition of the SDA line when SCL is HIGH is defined as a START bit. A LOW-to-HIGH transition of the SDA line when SCL is HIGH is defined as a STOP bit.

Each transmission must start with a START bit and end with a STOP bit. The bus is busy after a START bit and is only free again after a STOP bit has been transmitted.

I²C-BUS RECEIVER (MICROCONTROLLER WRITE MODE)

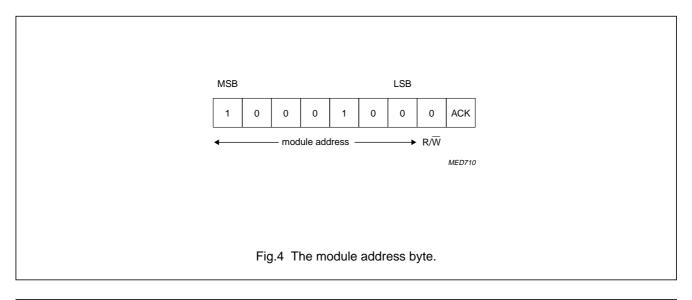
Each transmission to the I²C-bus receiver consists of at least three bytes following the START bit. Each byte is acknowledged by an acknowledge bit immediately following each byte. The first byte is the Module Address (MAD) byte, also called slave address byte. This includes the module address, 1000100 for the TDA4686. The TDA4686 is a slave receiver ($R/\overline{W} = 0$), therefore the module address byte is 10001000 (88H; see also Fig.4).

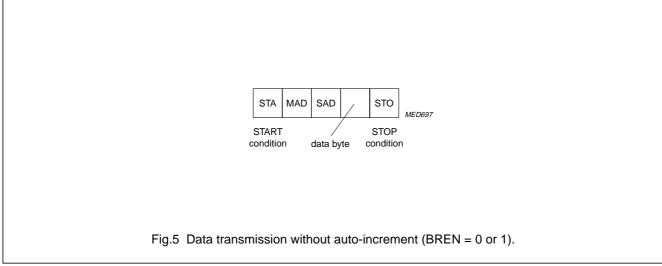
The length of a data transmission is unrestricted, but the module address and the correct subaddress must be transmitted before the data byte(s). The order of data transmission is shown in Figs 5 and 6. Without auto-increment (BREN = 0 or 1) the module address (MAD) byte is followed by a SubAddress (SAD)

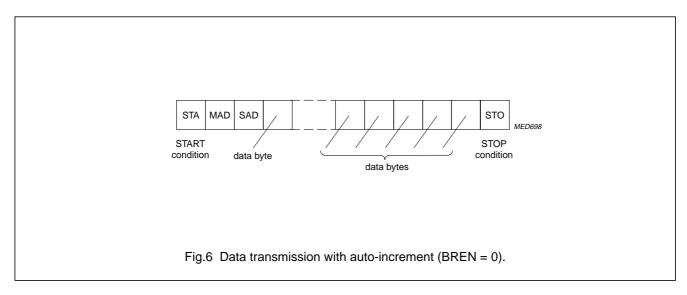
byte and one data byte only (see Fig.5).

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AUTO-INCREMENT

The auto-increment format enables quick slave receiver initialization by one transmission, when the I^2C -bus control bit BREN = 0 (see control register bits of Table 1). If BREN = 1 auto-increment is not possible.

If the auto-increment format is selected, the MAD byte is followed by a SAD byte and by the data bytes of consecutive subaddresses (see Fig.6).

All subaddresses from 00H to 0FH are automatically incremented, the subaddress counter wraps round from 0FH to 00H. Reserved subaddresses 07H, 08H, 09H, 0BH, 0EH and 0FH are treated as legal but have no effect. Subaddresses outside the range 00H and 0FH are not acknowledged by the device.

Subaddresses are stored in the TDA4686 to address the following parameters and functions (see Table 1):

- · Brightness adjust
- · Saturation adjust
- · Contrast adjust
- · Hue control voltage
- · RGB gain adjust
- · Peak drive limiting adjust
- · Control register functions.

The data bytes D7 to D0 (see Table 1) provide the data of the parameters and functions for video processing.

CONTROL REGISTER 1

NMEN (NTSC Matrix Enable):

- 0 = PAL/SECAM matrix
- 1 = NTSC matrix.

BREN (Buffer Register Enable):

0 = new data is executed as soon as it is received

1 = data is stored in buffer registers and is transferred to the data registers during the next vertical blanking interval.

The I²C-bus receiver does not accept any new data until this data is transferred into the data registers.

SC5 (SandCastle 5 V):

0 = 3-level sandcastle pulse

1 = 2-level (5 V) sandcastle pulse.

CONTROL REGISTER 2

FSON2 (Fast Switch 2 ON).

FSDIS2 (Fast Switch 2 Disable).

FSON1 (Fast Switch 1 ON).

FSDIS1 (Fast Switch 1 Disable).

The RGB input signals are selected by FSON2 and FSON1 or FSW₂ and FSW₁:

- FSON2 has priority over FSON1
- FSW₂ has priority over FSW₁
- FSDIS1 and FSDIS2 disable FSW₁ and FSW₂ (see Table 2).

BCOF (Black level Control Off):

0 = automatic cut-off control enabled

1 = automatic cut-off control disabled; RGB outputs are clamped to fixed DC levels.

When the supply voltage has dropped below approximately 6.0 V (usually occurs when the TV receiver is switched on or the supply voltage is interrupted) all data and function bits are set to 01H.

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Table 1 Subaddress (SAD) and data bytes; note 1

| FUNCTION | FUNCTION SAD | | | | | | | | LSB |
|---------------------|--------------|-----|----|------|------|--------|-------|--------|-------|
| FUNCTION | (HEX) | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| Brightness | 00 | 0 | 0 | A05 | A04 | A03 | A02 | A01 | A00 |
| Saturation | 01 | 0 | 0 | A15 | A14 | A13 | A12 | A11 | A10 |
| Contrast | 02 | 0 | 0 | A25 | A24 | A23 | A22 | A21 | A20 |
| Hue control voltage | 03 | 0 | 0 | A35 | A34 | A33 | A32 | A31 | A30 |
| Red gain | 04 | 0 | 0 | A45 | A44 | A43 | A42 | A41 | A40 |
| Green gain | 05 | 0 | 0 | A55 | A54 | A53 | A52 | A51 | A50 |
| Blue gain | 06 | 0 | 0 | A65 | A64 | A63 | A62 | A61 | A60 |
| Reserved | 07 | 0 | 0 | Х | Х | Х | Х | Х | Х |
| Reserved | 08 | 0 | 0 | Х | Х | Х | Х | Х | Х |
| Reserved | 09 | 0 | 0 | Х | Х | Х | Х | Х | Х |
| Peak drive limit | 0A | 0 | 0 | AA5 | AA4 | AA3 | AA2 | AA1 | AA0 |
| Reserved | 0B | Х | Х | Х | Х | Х | Х | Х | Х |
| Control register 1 | 0C | SC5 | Х | BREN | Х | NMEN | Х | Х | Х |
| Control register 2 | 0D | Х | Х | Х | BCOF | FSDIS2 | FSON2 | FSDIS1 | FSON1 |
| Reserved | 0E | Х | Х | Х | Х | Х | Х | Х | Х |
| Reserved | 0F | Х | Х | Х | Х | Х | Х | Х | Х |

Note

^{1.} X = don't care, but for software compatibility with other or future video ICs it is recommended to set all X to logic 0.

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Table 2 Signal input selection by the fast source switches; notes 1 to 4

| I ² C | -BUS CO | NTROL E | BITS | ANALOG SWI | TCH SIGNALS | IN | IPUT SELECTE | D |
|------------------|---------|---------|--------|-----------------------------|------------------------------|------|------------------|------|
| FSON2 | FSDIS2 | FSON1 | FSDIS1 | FSW ₂ (PIN 1) | FSW ₁ (PIN 13) | RGB₂ | RGB ₁ | Y/CD |
| L | L | L | L | L | L | | | ON |
| | | | | L | Н | | ON | |
| | | | | Н | X | ON | | |
| L | L | L | Н | L | X | | | ON |
| | | | | Н | Х | ON | | |
| L | L | Н | Х | L | Х | | ON | |
| | | | | Н | Х | ON | | |
| L | Н | L | L | Х | L | | | ON |
| | | | | X | Н | | ON | |
| L | Н | L | Н | X | Х | | | ON |
| L | Н | Н | Х | X | Х | | ON | |
| Н | Х | Х | Х | X | X | ON | | |

Notes

- 1. H: logic HIGH implies that the voltage >0.9 V.
- 2. L: logic LOW implies that the voltage <0.4 V.
- 3. X = don't care.
- 4. ON indicates the selected input signal.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

| SYMBOL | PARAMETER | MIN. | MAX. | UNIT |
|------------------|--|------|----------------------|------|
| V _P | supply voltage (pin 5) | _ | 8.8 | V |
| Vi | input voltage (pins 1 to 8, 10 to 13, 16, 21, 23 and 25) | -0.1 | +V _P | V |
| | input voltage (pins 15, 18 and 19) | -0.7 | V _P + 0.7 | V |
| | input voltage (pins 27 and 28) | -0.1 | +8.8 | V |
| V ₁₄ | sandcastle pulse voltage | -0.7 | V _P + 5.8 | V |
| l _{av} | average current (pins 20, 22 and 24) | -10 | +4 | mA |
| I _M | peak current (pins 20, 22 and 24) | -20 | +4 | mA |
| I ₂₆ | output current | -8 | +0.6 | mA |
| T _{stg} | storage temperature | -20 | +150 | °C |
| T _{amb} | operating ambient temperature | 0 | 70 | °C |
| P _{tot} | total power dissipation | | | |
| | SOT117-1 | _ | 1.2 | W |
| | SOT261-2 | _ | 1.0 | W |

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CHARACTERISTICS

All voltages are measured in test circuit of Fig.10 with respect to GND (pin 9); $V_P = 8.0 \text{ V}$; $T_{amb} = 25 \,^{\circ}\text{C}$; nominal signal amplitudes (black-to-white) at output pins 24, 22 and 20; nominal settings of brightness, contrast, saturation and white level control; without beam current or peak drive limiting; unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|-----------------------------|---|-------------------------|------|------|------|------|
| Supply (pin | 5) | | | | | • |
| V _P | supply voltage | | 7.2 | 8.0 | 8.8 | V |
| l _Р | supply current | | _ | 60 | _ | mA |
| Colour diffe | rence inputs [-(B - Y): pin 6; -(R - Y) |): pin 7] | | | | • |
| V _{6(p-p)} | -(B - Y) input (peak-to-peak value) | notes 1 and 2 | _ | 1.33 | _ | V |
| V _{7(p-p)} | -(R - Y) input (peak-to-peak value) | notes 1 and 2 | _ | 1.05 | _ | V |
| V _{6,7} | internal DC bias voltage | at black level clamping | _ | 4.1 | _ | V |
| I _{6,7} | input current | during line scan | _ | _ | 0.1 | μΑ |
| | | at black level clamping | 100 | _ | _ | μΑ |
| R _{6,7} | input resistance | | 10 | _ | _ | ΜΩ |
| Luminance/ | sync (VBS; Y: pin 8) | | | | • | |
| V _{i(p-p)} | luminance input voltage at pin 8 (peak-to-peak value) | note 2 | _ | 0.45 | _ | V |
| V _{8(bias)} | internal DC bias voltage | at black level clamping | _ | 4.1 | _ | V |
| I ₈ | input current | during line scan | _ | _ | 0.1 | μΑ |
| | | at black level clamping | 100 | _ | _ | μΑ |
| R ₈ | input resistance | | 10 | _ | _ | ΜΩ |
| RGB input 1 | (R ₁ : pin 10; G ₁ : pin 11; B ₁ : pin 12) | | | | | |
| V _{i(p-p)} | input voltage at pins 10, 11 and 12 (peak-to-peak value) | note 2 | _ | 0.7 | _ | V |
| V _{10/11/12(bias)} | internal DC bias voltage | at black level clamping | _ | 5.7 | _ | V |
| I _{10/11/12} | input current | during line scan | _ | _ | 0.1 | μΑ |
| | | at black level clamping | 100 | _ | _ | μΑ |
| R _{10/11/12} | input resistance | | 10 | _ | _ | ΜΩ |
| RGB input 2 | ? (R ₂ : pin 2, G ₂ : pin 3, B ₂ : pin 4) | | | | | |
| V _{i(p-p)} | input voltage at pins 2, 3 and 4 (peak-to-peak value) | note 2 | _ | 0.7 | _ | V |
| V _{2/3/4} | internal DC bias voltage | at black level clamping | _ | 5.7 | _ | V |
| I _{2/3/4} | input current | during line scan | _ | _ | 0.1 | μΑ |
| | | at black level clamping | 100 | _ | _ | μΑ |
| R _{2/3/4} | input resistance | | 10 | _ | _ | ΜΩ |

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| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|--|---|-------------------------------------|---|----------------------|--|
| Fast signal | switch FSW ₁ (pin 13) to select Y, CD | or R ₁ , G ₁ , B ₁ inputs (co | ntrol bits: s | ee Table 2) | • | • |
| V ₁₃ | voltage to select Y and CD | | _ | _ | 0.4 | V |
| | voltage to select R ₁ , G ₁ , B ₁ | | 0.9 | _ | 5.0 | V |
| R ₁₃ | internal resistance to ground | | _ | 4.0 | _ | kΩ |
| Δt | difference between transit times for signal switching and signal insertion | | _ | - | 10 | ns |
| Fast signal | switch FSW ₂ (pin 1) to select Y, CD/R | ₁ , G ₁ , B ₁ or R ₂ , G ₂ , B ₂ i | nputs (con | trol bits: se | e Table 2) | |
| V ₁ | voltage to select Y, CD/R ₁ , G ₁ , B ₁ | | _ | _ | 0.4 | V |
| | voltage to select R ₂ , G ₂ , B ₂ | | 0.9 | _ | 5.0 | V |
| R ₁ | internal resistance to ground | | _ | 4.0 | _ | kΩ |
| Δt | difference between transit times for signal switching and signal insertion | | - | - | 10 | ns |
| (10 | | | | | | |
| ام | saturation below maximum | at 23H | _ | 5 | _ | dB |
| Contrast ac | ljust [acts on internal RGB signals un | at 00H; f = 100 kHz der I ² C-bus control; su | | 50 02H (bit re | | dB |
| Contrast ac | | at 00H; f = 100 kHz der I ² C-bus control; su | | 50 02H (bit re | | dB |
| Contrast ac maximum c | ljust [acts on internal RGB signals un contrast); data byte 3FH for maximum | at 00H; f = 100 kHz der I ² C-bus control; su | | 50 02H (bit re | | dB |
| maximum c | ljust [acts on internal RGB signals un contrast); data byte 3FH for maximum imum contrast] | at 00H; f = 100 kHz der I ² C-bus control; su contrast, data byte 22 | | 50 02H (bit re nal contra | | dB .5% of a byte |
| Contrast ac maximum c 00H for min d _c Brightness of maximur | ljust [acts on internal RGB signals un contrast); data byte 3FH for maximum imum contrast] | at 00H; f = 100 kHz der I ² C-bus control; su contrast, data byte 22 at 22H at 00H under I ² C-bus control; | H for nomi - - subaddres | 50 02H (bit renal contrast | and dat | dB dB dB dB dB dB dB n 1.5% |
| Contrast ac maximum c 00H for min d _c Brightness of maximur data byte 0 | ljust [acts on internal RGB signals uncontrast); data byte 3FH for maximum imum contrast] contrast below maximum adjust [acts on internal RGB signals in brightness); data byte 3FH for maxion black level shift of nominal signal | at 00H; f = 100 kHz der I ² C-bus control; su contrast, data byte 22 at 22H at 00H under I ² C-bus control; | H for nomi - - subaddres | 50 02H (bit renal contrast | and dat | dB dB dB dB dB dB dB n 1.5% |
| Contrast ac maximum c 00H for min d _c Brightness of maximur data byte 0 | ljust [acts on internal RGB signals uncontrast); data byte 3FH for maximum simum contrast] contrast below maximum adjust [acts on internal RGB signals brightness); data byte 3FH for maxion brightness] | at 00H; f = 100 kHz der I ² C-bus control; su contrast, data byte 22 at 22H at 00H under I ² C-bus control; mum brightness, data | H for nomi - - subaddres | 50 02H (bit renal contrast 5 22 ss 00H (bit or nominal | - resolution | dB dB dB dB dB n 1.5% ss and |
| Contrast ac maximum o 00H for min d _c Brightness of maximur data byte 0 d _{br} | ljust [acts on internal RGB signals un contrast); data byte 3FH for maximum imum contrast] contrast below maximum adjust [acts on internal RGB signals in brightness); data byte 3FH for maxion brightness] black level shift of nominal signal amplitude referred to cut-off | at 00H; f = 100 kHz der I ² C-bus control; so contrast, data byte 22 at 22H at 00H under I ² C-bus control; mum brightness, data at 3FH at 00H baddresses 04H (red), | H for nomi - subaddres byte 26H fo | 50 02H (bit renal contrasts) 5 22 ss 00H (bit or nominal 30 -50 and 06H | resolution brightnes | dB .5% of a byte dB dB dB n 1.5% ss and |
| Contrast ac maximum of 00H for min d _c Brightness of maximum data byte 0d d _{br} | ljust [acts on internal RGB signals un contrast); data byte 3FH for maximum imum contrast] contrast below maximum adjust [acts on internal RGB signals in brightness); data byte 3FH for maxion brightness] black level shift of nominal signal amplitude referred to cut-off measurement level intiometers [under I²C-bus control; substitution internal resurrement signal amplitude referred to cut-off measurement level | at 00H; f = 100 kHz der I ² C-bus control; so contrast, data byte 22 at 22H at 00H under I ² C-bus control; mum brightness, data at 3FH at 00H baddresses 04H (red), | H for nomi - subaddres byte 26H fo | 50 02H (bit renal contrasts) 5 22 ss 00H (bit or nominal 30 -50 and 06H | resolution brightnes | dB .5% of a byte dB dB dB n 1.5% ss and |
| Contrast ac maximum c 00H for min d _c Brightness of maximur data byte 0d d _{br} | Ijust [acts on internal RGB signals un contrast); data byte 3FH for maximum imum contrast] contrast below maximum adjust [acts on internal RGB signals in brightness); data byte 3FH for maxion brightness] black level shift of nominal signal amplitude referred to cut-off measurement level intiometers [under I²C-bus control; sultainum gain; data byte 19H for nominal signal amplitude referred to cut-off measurement level | at 00H; f = 100 kHz der I ² C-bus control; so contrast, data byte 22 at 22H at 00H under I ² C-bus control; mum brightness, data at 3FH at 00H baddresses 04H (red), | H for nomi - subaddres byte 26H fo | 50 02H (bit renal contrasts) 5 22 ss 00H (bit or nominal 30 -50 and 06H | resolution brightnes | dB .5% of a byte dB dB dB .1.5% ss and |

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| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|-----------------------|---|------------------------------|--------------|------------|----------------------|------|
| RGB output | s (pins 24, 22 and 20; positive going | output signals; peak d | rive limiter | set = 3FH) | ; note 4 | |
| $V_{o(b-w)}$ | nominal output signals (black-to-white value) | | - | 2.0 | _ | V |
| | maximum output signals (black-to-white value) | | 3.0 | _ | _ | V |
| ΔV_{o} | spread between RGB output signals | | _ | _ | 10 | % |
| Vo | minimum output voltages | | _ | _ | 0.8 | V |
| | maximum output voltages | | 6.8 | _ | _ | V |
| V _{24,22,20} | voltage of cut-off measurement line equivalent to voltage during ultra-black | output clamping; BCOF = 1 | 2.3 | 2.5 | 2.7 | V |
| I _{int} | internal current sources | | _ | 5.0 | _ | mA |
| R_o | output resistance | | _ | 20 | _ | Ω |
| Frequency | response (measured with 10 M Ω , 30 p | F external load) | • | | | |
| f _{res} | frequency response of Y path (from pin 8 to pins 24, 22 and 20) | f = 14 MHz | - | _ | 3 | dB |
| | frequency response of CD path (from pins 7 to 24 and 6 to 20) | f = 12 MHz | _ | _ | 3 | dB |
| | frequency response of RGB ₁ path (from pins 10 to 24, 11 to 22 and 12 to 20) | f = 22 MHz | - | - | 3 | dB |
| | frequency response of RGB ₂ path (from pins 2 to 24, 3 to 22 and 4 to 20) | f = 22 MHz | _ | - | 3 | dB |
| Sandcastle | pulse detector (pin 14) | | | | | |
| CONTROL BIT | SC5 = 0; 3-LEVEL; notes 5 and 6 | | | | | |
| V ₁₄ | sandcastle pulse voltage | | | | | |
| | for horizontal and vertical blanking pulses | | 2.0 | 2.5 | 3.0 | V |
| | for horizontal pulses (line count) | | 4.0 | 4.5 | 5.0 | V |
| | for burst key pulses (clamping) | | 7.6 | _ | V _P + 5.8 | V |
| CONTROL BIT | SC5 = 1; 2-LEVEL; notes 5 and 6 | | • | • | • | |
| V ₁₄ | sandcastle pulse voltage | | | | | |
| | for horizontal and vertical blanking pulses | | 2.0 | 2.5 | 3.0 | V |
| | for burst key pulses | | 4.0 | 4.5 | V _P + 5.8 | V |
| GENERAL | | | | | | |
| I ₁₄ | output current | V ₁₄ = 0 V | _ | _ | -100 | μА |
| t _d | leading edge delay of the clamping pulse | | - | 0 | _ | μs |

Video processor with automatic cut-off control

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| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|-----------------------|---|--------------------------------------|------|------------------------|----------------------|------|
| Vertical flyk | pack (pin 18); note 6 | | • | • | • | • |
| V ₁₈ | vertical flyback pulse | for LOW | _ | _ | 2.5 | V |
| | | for HIGH | 4.5 | - | _ | V |
| | internal voltage | pin 18 open-circuit; note 7 | - | 5.0 | _ | V |
| I ₁₈ | input current | | _ | _ | 5 | μΑ |
| Average be | am current limiting (pin 15); note 8 | | | • | | • |
| V _{c(15)} | contrast reduction starting voltage | | _ | 4.0 | _ | V |
| $\Delta V_{c(15)}$ | voltage difference for full contrast reduction | | - | -2.0 | - | V |
| V _{br(15)} | brightness reduction starting voltage | | _ | 2.5 | _ | V |
| $\Delta V_{br(15)}$ | voltage difference for full brightness reduction | | _ | -1.6 | _ | V |
| | baddress 0AH]; note 9 | at 00H | | 1_ | 3.0 | l v |
| V _{20,22,24} | minimum RGB output voltages | at 00H | _ | _ | 3.0 | V |
| | maximum RGB output voltages | at 3FH | 7.0 | _ | _ | V |
| I ₁₆ | charge current | | _ | <u>-1</u> | _ | μΑ |
| | discharge current | during peak white | _ | 5 | _ | mA |
| V ₁₆ | internal voltage limitation | | 4.5 | _ | _ | V |
| V _{c(16)} | contrast reduction starting voltage | | _ | 4.0 | _ | V |
| $\Delta V_{c(16)}$ | voltage difference for full contrast reduction | | _ | -2.0 | _ | V |
| V _{br(16)} | brightness reduction starting voltage | | _ | 2.5 | _ | V |
| $\Delta V_{br(16)}$ | voltage difference for full brightness reduction | | - | -1.6 | _ | V |
| Automatic | cut-off control (pin 19); notes 6 and 10 | to 12; see Fig.8 | | | • | |
| V ₁₉ | external voltage | | _ | _ | V _P – 1.4 | V |
| I ₁₉ | output current | | _ | _ | -60 | μΑ |
| | input current | | 150 | _ | _ | μΑ |
| | additional input current | switch-on delay 1 | _ | 0.5 | _ | mA |
| V _{24,22,20} | monitor pulse amplitude (under I ² C-bus control; subaddress 0AH) | switch-on delay 1; note 11 | _ | V _{pdl} – 1.0 | - | V |
| V _{19(th)} | voltage threshold for picture tube cathode warming up | switch-on delay 1 | - | 4.5 | _ | V |
| V _{ref} | internally controlled voltage | during leakage measurement period | - | 2.7 | _ | V |
| ΔV_{19} | difference between V _{MEAS} (cut-off measurement voltage) and V _{ref} | | _ | 1.0 | _ | V |

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| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|--------------------------|--|--------------------------------------|---------|------------|------------|--------|
| Cut-off stor | rage (pins 25, 23 and 21) | • | • | • | • | -1 |
| I _{21,23,25} | charge and discharge currents | during cut-off measurement lines | _ | 0.3 | _ | mA |
| | input currents of storage inputs | outside measurement time | _ | _ | 0.1 | μΑ |
| Storage of I | leakage information (pin 17) | | • | • | • | • |
| I ₁₇ | charge and discharge currents | during leakage measurement period | - | 0.4 | _ | mA |
| | leakage current | outside measurement time | - | - | 0.1 | μΑ |
| V ₁₇ | threshold voltage for reset to switch-on state | | _ | 2.5 | _ | V |
| | l (under l ² C-bus control; subaddress (Itage and data byte 00H for minimum | | maximum | voltage; d | ata byte 2 | 0H for |
| V_{26} | output voltage | at 3FH | 4.8 | _ | _ | V |
| | | at 20H | _ | 3.0 | _ | V |
| | | at 00H | _ | _ | 1.2 | V |
| l _{int} | current of the internal current source at pin 26 | | 500 | _ | _ | μΑ |
| I ² C-bus rec | eiver clock SCL (pin 28) | | | | | |
| f _{SCL} | input frequency range | | 0 | _ | 100 | kHz |
| V _{IL} | LOW-level input voltage | | _ | _ | 1.5 | V |
| V _{IH} | HIGH-level input voltage | | 3.0 | _ | 6.0 | V |
| I _{IL} | LOW-level input current | | _ | _ | -10 | μΑ |
| I _{IH} | HIGH-level input current | | _ | _ | 10 | μΑ |
| t _L | clock pulse LOW | | 4.7 | _ | _ | μs |
| t _H | clock pulse HIGH | | 4.0 | _ | _ | μs |
| t _r | rise time | | _ | _ | 1.0 | μs |
| t _f | fall time | | _ | _ | 0.3 | μs |
| I ² C-bus rec | eiver data input/output SDA (pin 27) | | • | · | • | |
| V _{IL} | LOW-level input voltage | | _ | _ | 1.5 | V |
| V _{IH} | HIGH-level input voltage | | 3.0 | _ | 6.0 | V |
| I _{IL} | LOW-level input current | | - | _ | -10 | μΑ |
| I _{IH} | HIGH-level input current | | - | _ | 10 | μΑ |
| I _{OL} | LOW-level output current | | 3.0 | _ | 1- | mA |
| t _r | rise time | | _ | _ | 1.0 | μs |
| | fall times | | 1_ | _ | 0.3 | μs |
| t _f | fall time | | | - | 0.5 | μο |

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Notes to the characteristics

- 1. The values of the -(B-Y) and -(R-Y) colour difference input signals are for a 75% colour-bar signal.
- 2. The pins are capacitively coupled to a low ohmic source, with a recommended maximum output impedance of 600 Ω .
- 3. The white potentiometers affect the amplitudes of the RGB output signals.
- 4. The RGB outputs at pins 24, 22 and 20 are emitter followers with current sources.
- Sandcastle pulses are compared with internal threshold voltages independent of V_P. The threshold voltages separate the components of the sandcastle pulse. The particular component is generated when the voltage on pin 14 exceeds the defined internal threshold voltage.

The internal threshold voltages (control bit SC5 = 0) are:

- 1.5 V for horizontal and vertical blanking pulses
- 3.5 V for horizontal pulses
- 6.5 V for the burst key pulse.

The internal threshold voltages (control bit SC5 = 1) are:

- 1.5 V for horizontal and vertical blanking pulses
- 3.5 V for the burst key pulse.
- 6. Vertical signal blanking is determined by the vertical component of the sandcastle pulse. The leakage and the RGB cut-off measurement lines are positioned in the first four complete lines after the end of the vertical component. In this case, the RGB output signals are blanked until the end of the last measurement line; see Fig.8a. If an extra vertical flyback pulse VFB is applied to pin 18, the four measurement lines start in the first complete line after the end of the VFB pulse; see Fig.8b. In this case, the output signals are blanked either until the end of the last measurement line or until the end of the vertical component of the sandcastle pulse, according to which occurs last.
- 7. If no VFB pulse is applied, pin 18 can be left open-circuit or connected to V_P. If pin 18 is always LOW neither automatic cut-off control nor output clamping can happen.
- 8. Average beam current limiting reduces the contrast, at minimum contrast it reduces the brightness.
- 9. Peak drive limiting reduces the RGB outputs by reducing the contrast, at minimum contrast it reduces the brightness. The maximum RGB outputs are determined via the I²C-bus under subaddress 0AH. When an RGB output exceeds the maximum voltage, peak drive limiting is delayed by one horizontal line.
- 10. During leakage current measurement, the RGB channels are blanked to ultra-black level. During cut-off measurement one channel is set to the measurement pulse level, the other channels are blanked to ultra-black. Since the brightness adjust shifts the colour signal relative to the black level, the brightness adjust is disabled during the vertical blanking interval (see Figs 7 and 8).
- 11. During picture cathode warming up (first switch-on delay) the RGB outputs (pins 24, 22 and 20) are blanked to the ultra-black level during line scan. During the vertical blanking interval a white-level monitor pulse is fed out on the RGB outputs and the cathode currents are measured. When the voltage threshold on pin 19 is greater than 4.5 V, the monitor pulse is switched off and cut-off control is activated (second switch-on delay). As soon as cut-off control stabilizes, RGB output blanking is removed.
- 12. Range of cut-off measurement level at the RGB outputs is 1 to 5 V. The recommended value is 3 V.
- 13. The hue control output at pin 26 is an emitter follower with current source.

Video processor with automatic cut-off control

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Table 3 Demodulator axes and amplification factors

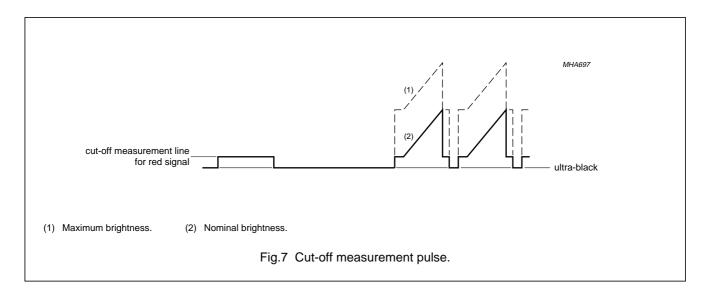
| PARAMETER | NTSC | PAL |
|-------------------------------|------|------|
| (B – Y)* demodulator axis | 0° | 0° |
| (R – Y)* demodulator axis | 115° | 90° |
| (R - Y)* amplification factor | 1.97 | 1.14 |
| (B – Y)* amplification factor | 2.03 | 2.03 |

Table 4 PAL/SECAM and NTSC matrix; note 1

| MATRIX | NMEN | | | |
|-----------|------|--|--|--|
| PAL/SECAM | 0 | | | |
| NTSC | 1 | | | |

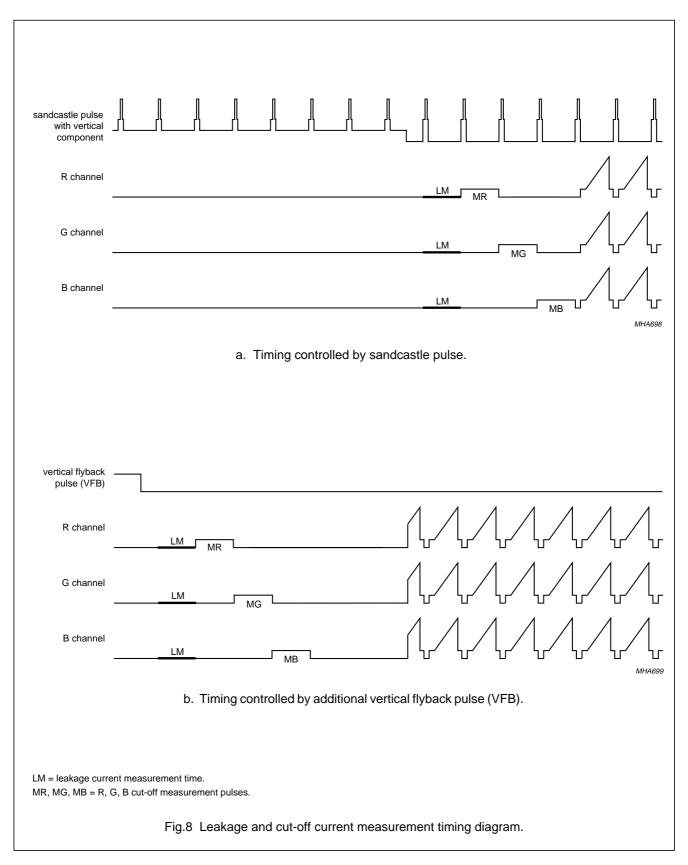
Note

1. PAL/SECAM signals are matrixed by the equation: $V_{G-Y} = -0.51V_{R-Y} - 0.19V_{B-Y}$ NTSC signals are matrixed by the equations (hue phase shift of -5 degrees): $V_{R-Y^*} = 1.57V_{R-Y} - 0.41V_{B-Y}$; $V_{G-Y^*} = -0.43V_{R-Y} - 0.11V_{B-Y}$; $V_{B-Y^*} = V_{B-Y}$ In the matrix equations: V_{R-Y} and V_{B-Y} are conventional PAL demodulation axes and amplitudes at the output of the NTSC demodulator. V_{G-Y^*} , V_{R-Y^*} and V_{B-Y^*} are the NTSC modified colour difference signals; this is equivalent to the demodulator axes and amplification factors shown in Table 3. $V_{G-Y^*} = -0.27V_{R-Y^*} - 0.22V_{B-Y^*}$.



Video processor with automatic cut-off control

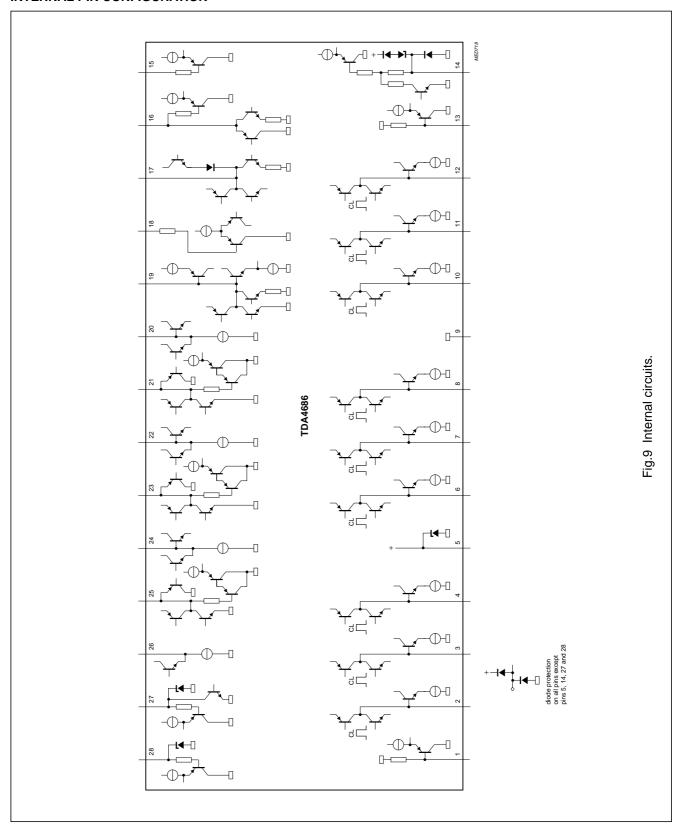
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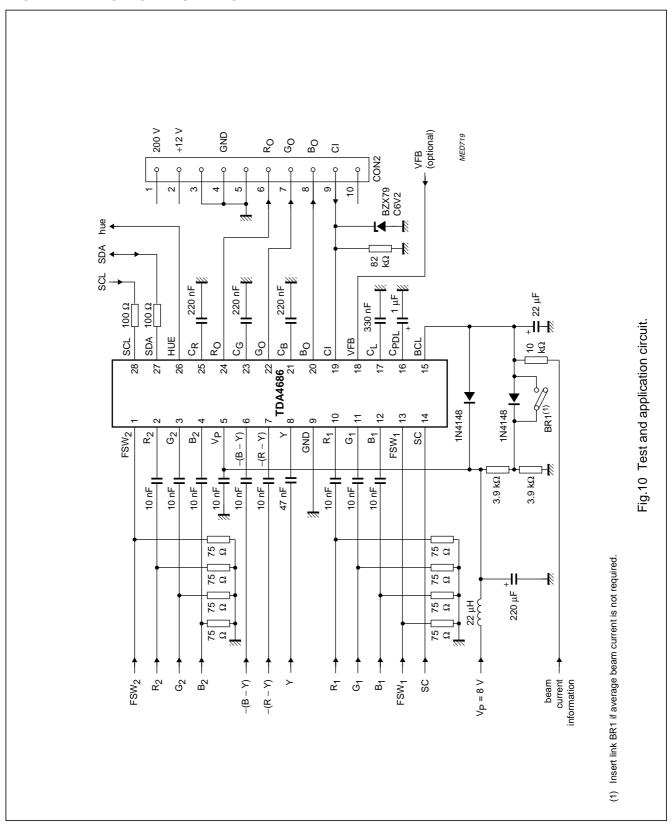
INTERNAL PIN CONFIGURATION



Video processor with automatic cut-off control

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TEST AND APPLICATION INFORMATION



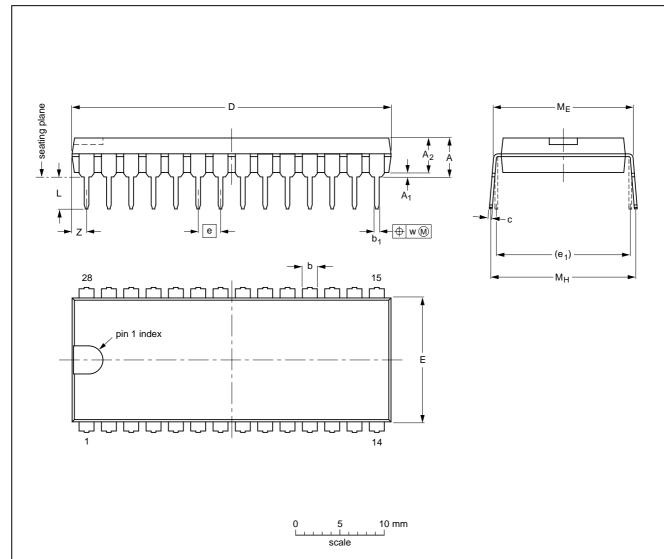
Video processor with automatic cut-off control

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PACKAGE OUTLINES

DIP28: plastic dual in-line package; 28 leads (600 mil)

SOT117-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

| UNIT | A max. | A ₁ min. | A ₂ max. | b | b ₁ | С | D ⁽¹⁾ | E ⁽¹⁾ | е | e ₁ | L | ME | Мн | w | Z ⁽¹⁾ max. |
|--------|-----------|------------------------|------------------------|----------------|----------------|----------------|------------------|------------------|------|----------------|--------------|----------------|----------------|------|--------------------------|
| mm | 5.1 | 0.51 | 4.0 | 1.7 1.3 | 0.53 0.38 | 0.32 0.23 | 36.0 35.0 | 14.1 13.7 | 2.54 | 15.24 | 3.9 3.4 | 15.80 15.24 | 17.15 15.90 | 0.25 | 1.7 |
| inches | 0.20 | 0.020 | 0.16 | 0.066 0.051 | 0.020 0.014 | 0.013 0.009 | 1.41 1.34 | 0.56 0.54 | 0.10 | 0.60 | 0.15 0.13 | 0.62 0.60 | 0.68 0.63 | 0.01 | 0.067 |

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

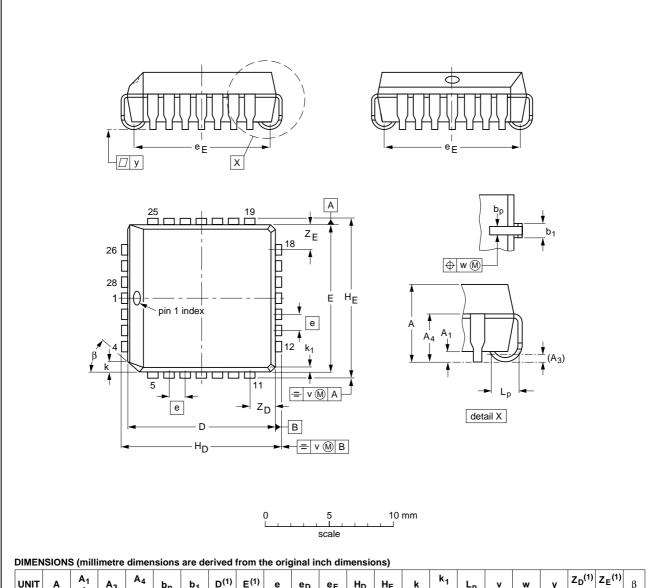
| OUTLINE | | REFER | ENCES | EUROPEAN | ISSUE DATE | |
|----------|--------|----------|-------|------------|------------|---------------------------------|
| VERSION | IEC | JEDEC | EIAJ | PROJECTION | | ISSUE DATE |
| SOT117-1 | 051G05 | MO-015AH | | | | 92-11-17 95-01-14 |

Video processor with automatic cut-off control

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PLCC28: plastic leaded chip carrier; 28 leads

SOT261-2



| UNIT | Α | A ₁ min. | A ₃ | A ₄ max. | bp | b ₁ | D ⁽¹⁾ | E ⁽¹⁾ | е | e _D | eE | H _D | HE | k | k ₁ max. | Lp | v | w | у | Z _D ⁽¹⁾ max. | Z _E ⁽¹⁾ max. | β |
|--------|----------------|------------------------|----------------|------------------------|----------------|----------------|------------------|------------------|------|----------------|----------------|----------------|----------------|----------------|------------------------|----------------|-------|-------|-------|---------------------------------------|---------------------------------------|-----|
| mm | 4.57 4.19 | 0.51 | 0.25 | 3.05 | 0.53 0.33 | 0.81 0.66 | 11.58 11.43 | 11.58 11.43 | 1.27 | 10.92 9.91 | 10.92 9.91 | | 12.57 12.32 | 1.22 1.07 | 0.51 | 1.44 1.02 | 0.18 | 0.18 | 0.10 | 2.16 | 2.16 | 45° |
| inches | 0.180 0.165 | 0.020 | 0.01 | 0.12 | 0.021 0.013 | 0.032 0.026 | 0.456 0.450 | 0.456 0.450 | 0.05 | 0.430 0.390 | 0.430 0.390 | 0.495 0.485 | 0.495 0.485 | 0.048 0.042 | 0.020 | 0.057 0.040 | 0.007 | 0.007 | 0.004 | 0.085 | 0.085 | |

Note

1. Plastic or metal protrusions of 0.01 inches maximum per side are not included.

| OUTLINE | | REFER | EUROPEAN | ISSUE DATE | | | |
|----------|-----|-------|----------|------------|------------|---------------------------------|--|
| VERSION | IEC | JEDEC | EIAJ | | PROJECTION | ISSUE DATE | |
| SOT261-2 | | | | | | 92-11-17 95-02-25 | |

Video processor with automatic cut-off control

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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "IC Package Databook" (order code 9398 652 90011).

DIP

SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

PLCC

REFLOW SOLDERING

Reflow soldering techniques are suitable for all PLCC packages.

The choice of heating method may be influenced by larger PLCC packages (44 leads, or more). If infrared or vapour phase heating is used and the large packages are not absolutely dry (less than 0.1% moisture content by weight), vaporization of the small amount of moisture in them can cause cracking of the plastic body. For more information, refer to the Drypack chapter in our "Quality Reference Handbook" (order code 9397 750 00192).

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 $^{\circ}$ C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at $45\,^{\circ}\text{C}$.

WAVE SOLDERING

Wave soldering techniques can be used for all PLCC packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 $^{\circ}$ C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 $^{\circ}$ C.

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DEFINITIONS

| Data sheet status | |
|---------------------------|---|
| Objective specification | This data sheet contains target or goal specifications for product development. |
| Preliminary specification | This data sheet contains preliminary data; supplementary data may be published later. |
| Product specification | This data sheet contains final product specifications. |
| Limiting values | |

Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

PURCHASE OF PHILIPS I2C COMPONENTS



Purchase of Philips I²C components conveys a license under the Philips' I²C patent to use the components in the I²C system provided the system conforms to the I²C specification defined by Philips. This specification can be ordered using the code 9398 393 40011.

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NOTES

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